



**THE DATASHEET OF  
ADS7809U/1KE4**





# 16-Bit 10 $\mu$ s Serial CMOS Sampling ANALOG-TO-DIGITAL CONVERTER

## FEATURES

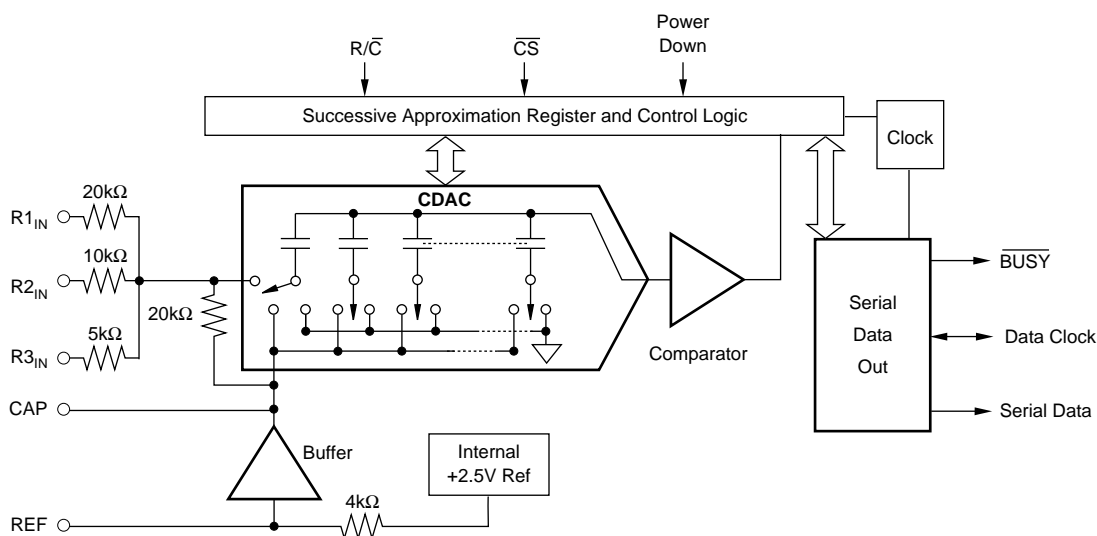
- 100kHz SAMPLING RATE
- 86dB SINAD WITH 20kHz INPUT
- $\pm 2$ LSB INL
- DNL: 16 Bits No Missing Codes
- SIX SPECIFIED INPUT RANGES
- SERIAL OUTPUT
- SINGLE +5V SUPPLY OPERATION
- PIN-COMPATIBLE WITH 12-BIT ADS7808
- USES INTERNAL OR EXTERNAL REFERENCE
- 100mW MAX POWER DISSIPATION
- 0.3" SO-20
- SIMPLE DSP INTERFACE

## DESCRIPTION

The ADS7809 is a complete 16-bit sampling Analog-to-Digital (A/D) converter using state-of-the-art CMOS structures. It contains a 16-bit capacitor-based Successive Approximation Register (SAR) A/D converter with sample-and-hold, reference, clock, and a serial data interface. Data can be outputted using the internal clock, or can be synchronized to an external data clock. The ADS7809 also provides an output synchronization pulse for ease of use with standard DSP processors.

The ADS7809 is specified at a 100kHz sampling rate, and specified over the full temperature range. Laser-trimmed scaling resistors provide various input ranges including  $\pm 10$ V and 0V to 5V, while an innovative design operates from a single +5V supply, with power dissipation under 100mW.

The ADS7809 is available in a 0.3" SO-20, and is fully specified for operation over the industrial  $-40^{\circ}\text{C}$  to  $+85^{\circ}\text{C}$  range.



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## ABSOLUTE MAXIMUM RATINGS<sup>(1)</sup>

|   |   |
|---|---|
| Analog Inputs: R1 <sub>IN</sub> .....         | ±25V  |
| R2 <sub>IN</sub> .....                        | ±25V  |
| R3 <sub>IN</sub> .....                        | ±25V  |
| REF .....                                     | V <sub>ANA</sub> + 0.3V to AGND2 – 0.3V                           |
| CAP .....                                     | Indefinite Short to AGND2,<br>Momentary Short to V <sub>ANA</sub> |
| Ground Voltage Differences: DGND, AGND2 ..... | ±0.3V   |
| V <sub>ANA</sub> .....                        | 7V  |
| V <sub>DIG</sub> to V <sub>ANA</sub> .....    | +0.3  |
| V <sub>DIG</sub> .....                        | 7V  |
| Digital Inputs .....                          | –0.3V to V <sub>DIG</sub> + 0.3V                                  |
| Maximum Junction Temperature .....            | +165°C  |
| Internal Power Dissipation .....              | 700mW   |
| Lead Temperature (soldering, 10s) .....       | +300°C  |

NOTE: (1) Stresses above those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. Exposure to absolute maximum conditions for extended periods may affect device reliability.



## ELECTROSTATIC DISCHARGE SENSITIVITY

This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

## PACKAGE/ORDERING INFORMATION<sup>(1)</sup>

| PRODUCT   | MAXIMUM LINEARITY ERROR (LSB) | NO MISSING CODE LEVEL (LSB) | MINIMUM SIGNAL-TO-(NOISE + DISTORTION) RATIO (dB) | PACKAGE-LEAD | PACKAGE DESIGNATOR | SPECIFIED TEMPERATURE RANGE | PACKAGE MARKING | ORDERING NUMBER | TRANSPORT MEDIA, QUANTITY |
|-----------|-------------------------------|-----------------------------|---|--------------|--------------------|-----------------------------|-----------------|-----------------|---------------------------|
| ADS7809U  | ±3                            | 15                          | 83  | SO-20        | DW                 | –40°C to +85°C              | ADS7809U        | ADS7809U        | Rail, 38                  |
| "         | "                             | "                           | "   | "            | "                  | "                           | "               | ADS7809U/1K     | Tape and Reel, 1000       |
| ADS7809UB | ±2                            | 16                          | 86  | "            | "                  | "                           | ADS7809UB       | ADS7809UB       | Rail, 38                  |
| "         | "                             | "                           | "   | "            | "                  | "                           | "               | ADS7809UB/1K    | Tape and Reel, 1000       |

NOTE: (1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at [www.ti.com](http://www.ti.com).



# ELECTRICAL CHARACTERISTICS (Cont.)

At  $T_A = -40^\circ\text{C}$  to  $+85^\circ\text{C}$ ,  $f_S = 100\text{kHz}$ ,  $V_{\text{DIG}} = V_{\text{ANA}} = +5\text{V}$ , using internal reference and fixed resistors as shown in Figure 4, unless otherwise specified.

| PARAMETER   | CONDITIONS  | ADS7809U |     |         | ADS7809UB |     |     | UNITS              |
|---|---|----------|-----|---------|-----------|-----|-----|--------------------|
|   |   | MIN      | TYP | MAX     | MIN       | TYP | MAX |                    |
| <b>DIGITAL OUTPUTS</b>                              |   |          |     |         |           |     |     |                    |
| Data Format   |   |          |     |         |           |     |     |                    |
| Data Co   |   |          |     |         |           |     |     |                    |
| Pipeline Delay                                      |   |          |     |         |           |     |     |                    |
| Data Clock  |   |          |     |         |           |     |     |                    |
| Internal<br>(Output Only When<br>Transmitting Data) | EXT/ $\overline{\text{INT}}$ LOW                                      |          | 2.3 |         |           | *   |     | MHz                |
| External<br>(Can Run Continually)                   | EXT/ $\overline{\text{INT}}$ HIGH                                     | 0.1      |     | 10      | *         |     | *   | MHz                |
| $V_{\text{OL}}$                                     | $I_{\text{SINK}} = 1.6\text{mA}$                                      |          |     | +0.4    |           |     | *   | V                  |
| $V_{\text{OH}}$                                     | $I_{\text{SOURCE}} = 500\mu\text{A}$                                  | +4       |     |         | *         |     | *   | V                  |
| Leakage Current                                     | High-Z State,<br>$V_{\text{OUT}} = 0\text{V}$ to $V_{\text{DIG}}$     |          |     | $\pm 5$ |           |     | *   | $\mu\text{A}$      |
| Output Capacitance                                  | High-Z State  |          |     | 15      |           |     | *   | pF                 |
| <b>POWER SUPPLIES</b>                               |   |          |     |         |           |     |     |                    |
| Specified Performance                               | Must be $\leq V_{\text{ANA}}$   | +4.75    | +5  | +5.25   | *         | *   | *   | V                  |
| $V_{\text{DIG}}$                                    |   | +4.75    | +5  | +5.25   | *         | *   | *   | V                  |
| $V_{\text{ANA}}$                                    |   |          | 0.3 |         |           | *   |     | mA                 |
| $I_{\text{DIG}}$                                    |   |          | 16  |         |           | *   |     | mA                 |
| $I_{\text{ANA}}$                                    |   |          |     | 100     |           | *   | *   | mW                 |
| Power Dissipation: PWRD LOW                         | $V_{\text{ANA}} = V_{\text{DIG}} = 5\text{V}$ , $f_S = 100\text{kHz}$ |          |     |         |           | *   | *   | mW                 |
| Power Dissipation: PWRD HIGH                        |   |          | 50  |         |           | *   | *   | $\mu\text{W}$      |
| <b>TEMPERATURE RANGE</b>                            |   |          |     |         |           |     |     |                    |
| Specified Performance                               |   | -40      |     | +85     | *         |     | *   | $^\circ\text{C}$   |
| Derated Performance                                 |   | -55      |     | +125    | *         |     | *   | $^\circ\text{C}$   |
| Storage   |   | -65      |     | +150    | *         |     | *   | $^\circ\text{C}$   |
| Thermal Resistance ( $\theta_{\text{JA}}$ )         |   |          |     |         |           |     |     |                    |
| SO  |   |          | 75  |         |           | *   |     | $^\circ\text{C/W}$ |

\* Same as specification for ADS7809U.

NOTES: (1) LSB means Least Significant Bit. For the  $\pm 10\text{V}$  input range, one LSB is  $305\mu\text{V}$ .

(2) Typical rms noise at worst case transitions and temperatures.

(3) As measured with fixed resistors shown in Figure 4. Adjustable to zero with external potentiometer.

(4) For bipolar input ranges, full-scale error is the worst case of -Full Scale or +Full Scale untrimmed deviation from ideal first and last code transitions, divided by the transition voltage (not divided by the full-scale range) and includes the effect of offset error. For unipolar input ranges, full-scale error is the deviation of the last code transition divided by the transition voltage. It also includes the effect of offset error.

(5) All specifications in dB are referred to a full-scale  $\pm 10\text{V}$  input.

(6) Full-Power Bandwidth defined as Full-Scale input frequency at which Signal-to-(Noise + Distortion) degrades to 60dB.

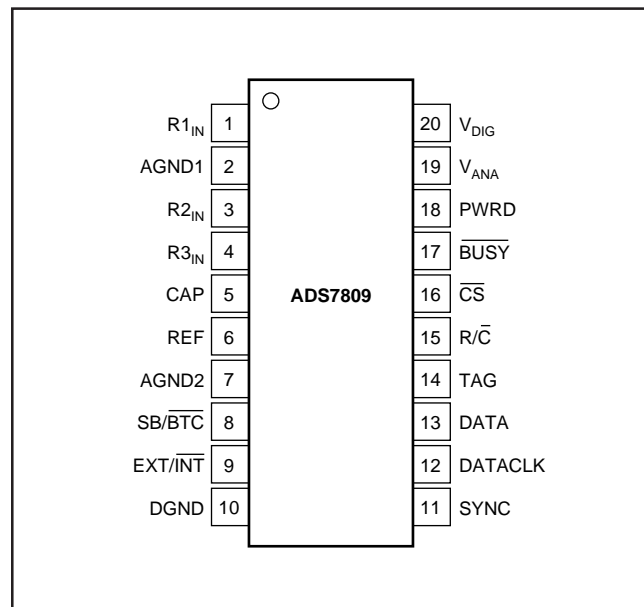
(7) Recovers to specified performance after  $2 \cdot \text{FS}$  input overvoltage.

(8) The minimum  $V_{\text{IH}}$  level for the DATACLK signal is 3V.

## PIN ASSIGNMENTS

| PIN # | NAME             | DESCRIPTION  |
|-------|------------------|--|
| 1     | R1 <sub>IN</sub> | Analog Input. See Table I and Figure 4 for input range connections.  |
| 2     | AGND1            | Analog Ground. Used internally as ground reference point. Minimal current flow.  |
| 3     | R2 <sub>IN</sub> | Analog Input. See Table I and Figure 4 for input range connections.  |
| 4     | R3 <sub>IN</sub> | Analog Input. See Table I and Figure 4 for input range connections.  |
| 5     | CAP              | Reference Buffer Capacitor. 2.2μF Tantalum to ground.  |
| 6     | REF              | Reference Input/Output. Outputs internal 2.5V reference. Can also be driven by external system reference. In both cases, bypass to ground with a 2.2μF Tantalum capacitor.   |
| 7     | AGND2            | Analog Ground  |
| 8     | SB/BTC           | Select Straight Binary or Binary Two's Complement data output format. If HIGH, data will be output in a Straight Binary format. If LOW, data will be output in a Binary Two's Complement format.   |
| 9     | EXT/INT          | Select External or Internal Clock for transmitting data. If HIGH, data will be output synchronized to the clock input on DATACLK. If LOW, a convert command will initiate the transmission of the data from the previous conversion, along with 16 clock pulses output on DATACLK.   |
| 10    | DGND             | Digital Ground   |
| 11    | SYNC             | Synch Output. If EXT/INT is HIGH, either a rising edge on R/C with CS LOW or a falling edge on CS with R/C HIGH will output a pulse on SYNC synchronized to the external DATACLK.  |
| 12    | DATACLK          | Either an input or an output depending on the EXT/INT level. Output data will be synchronized to this clock. If EXT/INT is LOW, DATACLK will transmit 16 pulses after each conversion, and then remain LOW between conversions.  |
| 13    | DATA             | Serial Data Output. Data will be synchronized to DATACLK, with the format determined by the level of SB/BTC. In the external clock mode, after 16 bits of data, the ADS7809 will output the level input on TAG as long as CS is LOW and R/C is HIGH (see Figure 3). If EXT/INT is LOW, data will be valid on both the rising and falling edges of DATACLK, and between conversions DATA will stay at the level of the TAG input when the conversion was started. |
| 14    | TAG              | Tag Input for use in external clock mode. If EXT/INT is HIGH, digital data input on TAG will be output on DATA with a delay of 16 DATACLK pulses as long as CS is LOW and R/C is HIGH. See Figure 3.   |
| 15    | R/C              | Read/Convert Input. With CS LOW, a falling edge on R/C puts the internal sample-and-hold into the hold state and starts a conversion. When EXT/INT is LOW, this also initiates the transmission of the data results from the previous conversion. If EXT/INT is HIGH, a rising edge on R/C with CS LOW, or a falling edge on CS with R/C HIGH, transmits a pulse on SYNC and initiates the transmission of data from the previous conversion.                    |
| 16    | CS               | Chip Select. Internally OR'ed with R/C.  |
| 17    | BUSY             | Busy Output. Falls when a conversion is started, and remains LOW until the conversion is completed and the data is latched into the output shift register. CS or R/C must be HIGH when BUSY rises, or another conversion will start without time for signal acquisition.   |
| 18    | PWRD             | Power Down Input. If HIGH, conversions are inhibited and power consumption is significantly reduced. Results from the previous conversion are maintained in the output shift register.   |
| 19    | V <sub>ANA</sub> | Analog Supply Input. Nominally +5V. Connect directly to pin 20, and decouple to ground with 0.1μF ceramic and 10μF tantalum capacitors.  |
| 20    | V <sub>DIG</sub> | Digital Supply Input. Nominally +5V. Connect directly to pin 19. Must be ≤ V <sub>ANA</sub> .  |

## PIN CONFIGURATION



| ANALOG INPUT RANGE | CONNECT R1 <sub>IN</sub> VIA 200Ω TO | CONNECT R2 <sub>IN</sub> VIA 100Ω TO | CONNECT R3 <sub>IN</sub> TO | IMPEDANCE |
|--------------------|--------------------------------------|--------------------------------------|-----------------------------|-----------|
| ±10V               | V <sub>IN</sub>                      | AGND                                 | CAP                         | 22.9kΩ    |
| ±5V                | AGND                                 | V <sub>IN</sub>                      | CAP                         | 13.3kΩ    |
| ±3.33V             | V <sub>IN</sub>                      | V <sub>IN</sub>                      | CAP                         | 10.7kΩ    |
| 0V to 10V          | AGND                                 | V <sub>IN</sub>                      | AGND                        | 13.3kΩ    |
| 0V to 5V           | AGND                                 | AGND                                 | V <sub>IN</sub>             | 10.0kΩ    |
| 0V to 4V           | V <sub>IN</sub>                      | AGND                                 | V <sub>IN</sub>             | 10.7kΩ    |

TABLE I. Input Range Connections. See Figure 4 for complete information.

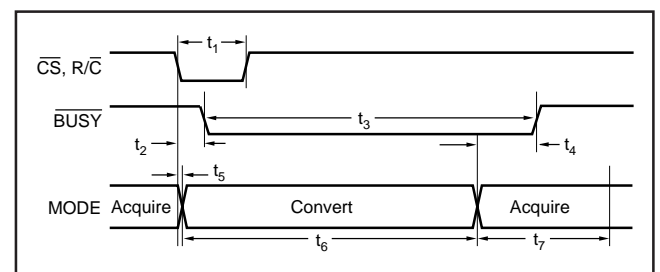


FIGURE 1. Basic Conversion Timing.

| SYMBOL      | DESCRIPTION   | MIN | TYP | MAX          | UNITS         |
|-------------|---|-----|-----|--------------|---------------|
| $t_1$       | Convert Pulse Width   | 40  |     | 6000         | ns            |
| $t_2$       | $\overline{\text{BUSY}}$ Delay                                      |     |     | 65           | ns            |
| $t_3$       | $\overline{\text{BUSY}}$ LOW  |     |     | 8            | $\mu\text{s}$ |
| $t_4$       | $\overline{\text{BUSY}}$ Delay After End of Conversion              |     | 220 |              | ns            |
| $t_5$       | Aperture Delay  |     | 40  |              | ns            |
| $t_6$       | Conversion Time   |     | 7.6 | 8            | $\mu\text{s}$ |
| $t_7$       | Acquisition Time  |     |     | 2            | $\mu\text{s}$ |
| $t_6 + t_7$ | Throughput Time   |     | 9   | 10           | $\mu\text{s}$ |
| $t_8$       | $\text{R}/\overline{\text{C}}$ LOW to DATACLK Delay                 |     | 450 |              | ns            |
| $t_9$       | DATACLK Period  |     | 440 |              | ns            |
| $t_{10}$    | Data Valid to DATACLK HIGH Delay                                    | 20  | 75  |              | ns            |
| $t_{11}$    | Data Valid After DATACLK LOW Delay                                  | 100 | 125 |              | ns            |
| $t_{12}$    | External DATACLK  | 100 |     |              | ns            |
| $t_{13}$    | External DATACLK HIGH   | 20  |     |              | ns            |
| $t_{14}$    | External DATACLK LOW  | 30  |     |              | ns            |
| $t_{15}$    | DATACLK HIGH Setup Time   | 20  |     | $t_{12} + 5$ | ns            |
| $t_{16}$    | $\text{R}/\overline{\text{C}}$ to $\overline{\text{CS}}$ Setup Time | 10  |     |              | ns            |
| $t_{17}$    | SYNC Delay After DATACLK HIGH                                       | 15  |     | 35           | ns            |
| $t_{18}$    | Data Valid Delay  | 25  |     | 55           | ns            |
| $t_{19}$    | $\overline{\text{CS}}$ to Rising Edge Delay                         | 25  |     |              | ns            |
| $t_{20}$    | Data Available after $\overline{\text{CS}}$ LOW                     | 6   |     |              | $\mu\text{s}$ |

TABLE II. Conversion and Data Timing.  $T_A = -40^\circ\text{C}$  to  $+85^\circ\text{C}$ .

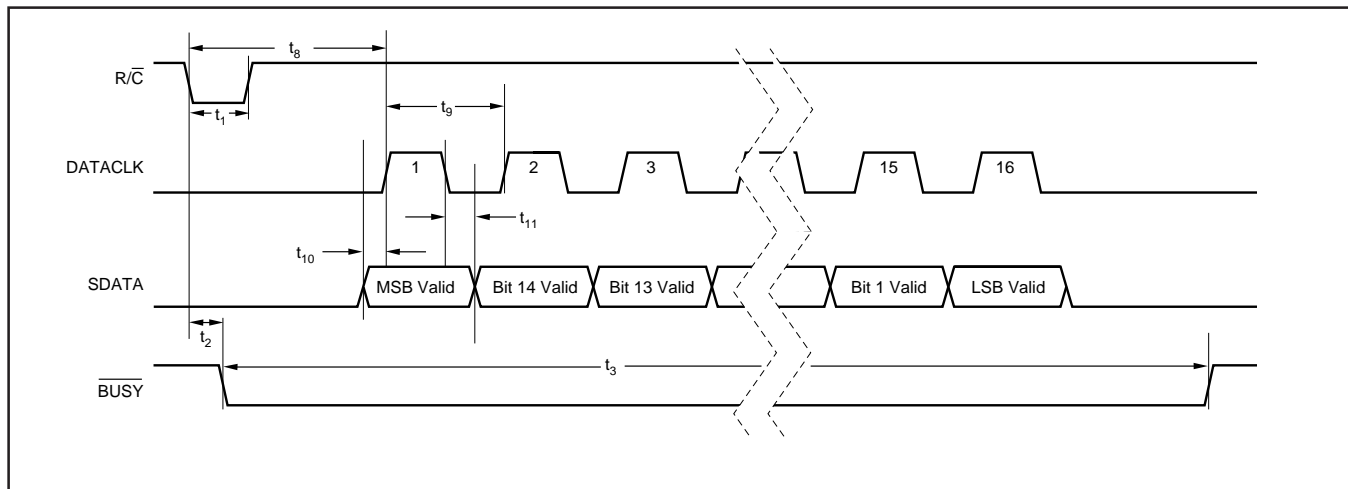


FIGURE 2. Serial Data Timing Using Internal Clock. ( $\overline{\text{CS}}$ ,  $\text{EXT}/\overline{\text{INT}}$  and TAG Tied LOW.)

| SPECIFIC FUNCTION  | $\overline{CS}$ | $R/\overline{C}$ | $\overline{BUSY}$ | $\overline{EXT}/\overline{INT}$ | DATACLK | PWRD | SB/ $\overline{BTC}$ | OPERATION  |
|--|-----------------|------------------|-------------------|---------------------------------|---------|------|----------------------|--|
| Initiate Conversion and Output Data Using Internal Clock | 1 > 0           | 0                | 1                 | 0                               | Output  | 0    | x                    | Initiates conversion "n". Data from conversion "n - 1" clocked out on DATA synchronized to 16 clock pulses output on DATACLK.                            |
|  | 0               | 1 > 0            | 1                 | 0                               | Output  | 0    | x                    | Initiates conversion "n". Data from conversion "n - 1" clocked out on DATA synchronized to 16 clock pulses output on DATACLK.                            |
| Initiate Conversion and Output Data Using External Clock | 1 > 0           | 0                | 1                 | 1                               | Input   | 0    | x                    | Initiates conversion "n".  |
|  | 0               | 1 > 0            | 1                 | 1                               | Input   | 0    | x                    | Initiates conversion "n".  |
|  | 1 > 0           | 1                | 1                 | 1                               | Input   | x    | x                    | Outputs a pulse on SYNC followed by data from conversion "n" clocked out synchronized to external DATACLK.   |
|  | 1 > 0           | 1                | 0                 | 1                               | Input   | 0    | x                    | Outputs a pulse on SYNC followed by data from conversion "n - 1" clocked out synchronized to external DATACLK. <sup>(1)</sup> Conversion "n" in process. |
| Incorrect Conversions                                    | 0               | 0                | 0 > 1             | x                               | x       | 0    | x                    | $\overline{CS}$ or $R/\overline{C}$ must be HIGH or a new conversion will be initiated without time for acquisition.                                     |
|  | x               | x                | x                 | x                               | x       | 0    | x                    | Analog circuitry powered. Conversion can proceed.  |
| Power-Down   | x               | x                | x                 | x                               | x       | 1    | x                    | Analog circuitry disabled. Data from previous conversion maintained in output registers.   |
|  | x               | x                | x                 | x                               | x       | x    | 1                    |  |
| Selecting Output Format                                  | x               | x                | x                 | x                               | x       | x    | 0                    | Serial data is output in Binary Two's Complement format.   |
|  | x               | x                | x                 | x                               | x       | x    | 1                    | Serial data is output in Straight Binary format.   |

NOTE: (1) See Figure 3b for constraints on previous data valid during conversion.

TABLE III. Control Truth Table.

| DESCRIPTION                 | ANALOG INPUT |              |              |             |            |            | DIGITAL OUTPUT                                     |          |   |          |
|-----------------------------|--------------|--------------|--------------|-------------|------------|------------|--|----------|---|----------|
|                             |              |              |              |             |            |            | BINARY TWO'S COMPLEMENT (SB/ $\overline{BTC}$ LOW) |          | STRAIGHT BINARY (SB/ $\overline{BTC}$ HIGH) |          |
|                             |              |              |              |             |            |            | BINARY CODE  | HEX CODE | BINARY CODE                                 | HEX CODE |
| Full-Scale Range            | $\pm 10$     | $\pm 5$      | $\pm 3.33V$  | 0V to 10V   | 0V to 5V   | 0V to 4V   |  |          |   |          |
| Least Significant Bit (LSB) | 305 $\mu V$  | 153 $\mu V$  | 102 $\mu V$  | 153 $\mu V$ | 76 $\mu V$ | 61 $\mu V$ |  |          |   |          |
| +Full Scale (FS - 1LSB)     | 9.999695V    | 4.999847V    | 3.333231V    | 9.999847V   | 4.999924V  | 3.999939V  | 0111 1111 1111 1111                                | 7FFF     | 1111 1111 1111 1111                         | FFFF     |
| Midscale                    | 0V           | 0V           | 0V           | 5V          | 2.5V       | 2V         | 0000 0000 0000 0000                                | 0000     | 1000 0000 0000 0000                         | 8000     |
| One LSB Below Midscale      | -305 $\mu V$ | -153 $\mu V$ | -102 $\mu V$ | 4.999847V   | 2.499924V  | 1.999939V  | 1111 1111 1111 1111                                | FFFF     | 0111 1111 1111 1111                         | 7FFF     |
| -Full Scale                 | -10V         | -5V          | -3.333333V   | 0V          | 0V         | 0V         | 1000 0000 0000 0000                                | 8000     | 0000 0000 0000 0000                         | 0000     |

TABLE IV. Output Codes and Ideal Input Voltages.

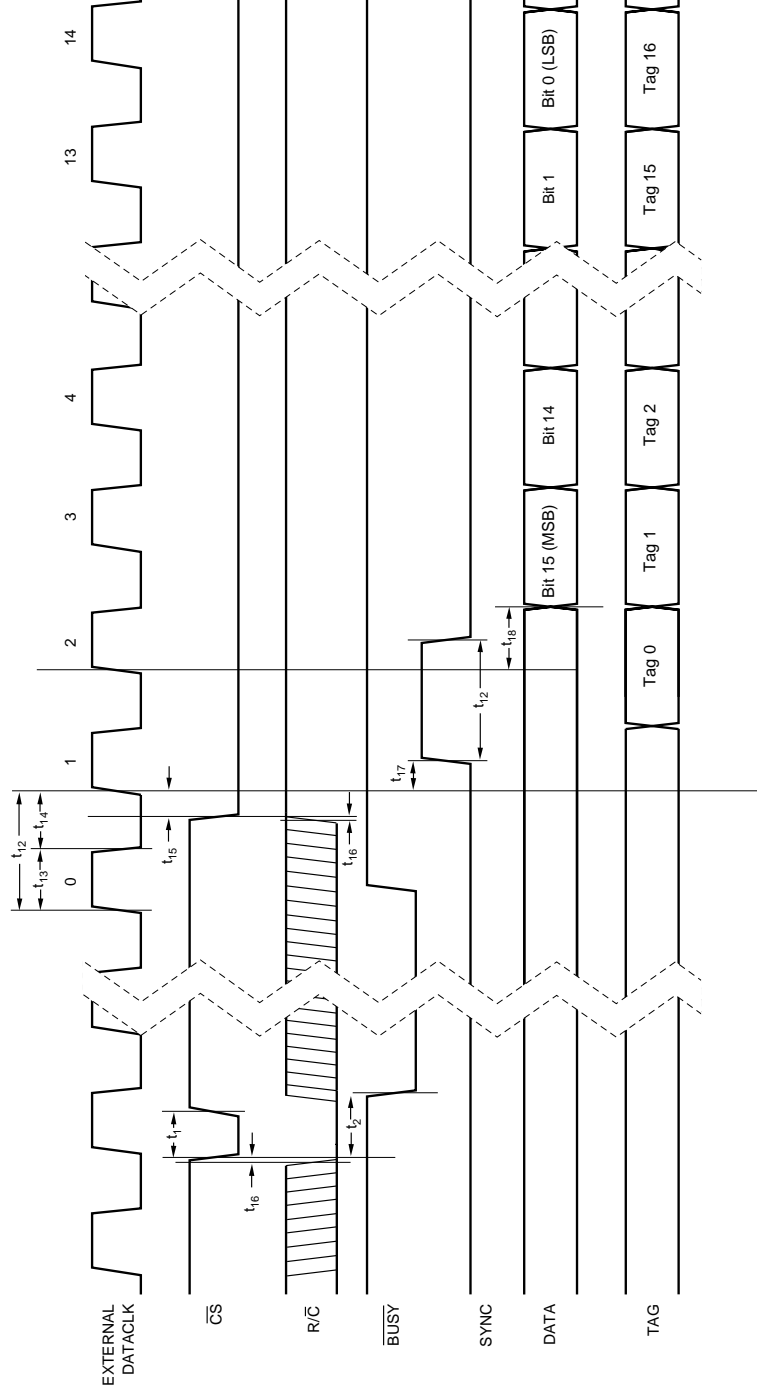


FIGURE 3a. Conversion and Read Timing with External Clock. (EXT/INT Tied High.) Read After Conversion.

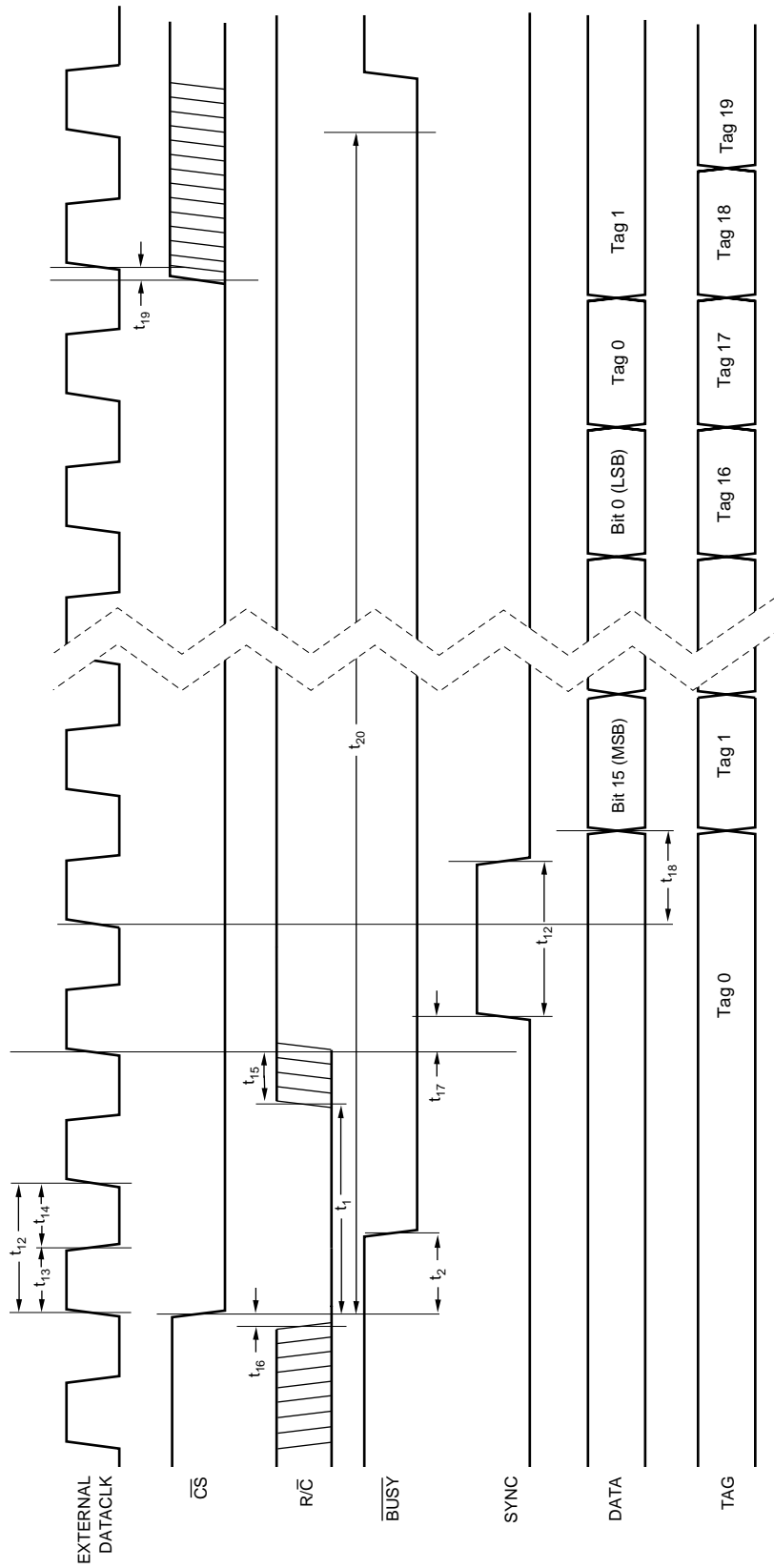


FIGURE 3b. Conversion and Read Timing with External Clock. (EXT/INT Tied High.) Read During Conversion (Previous Conversion Results).

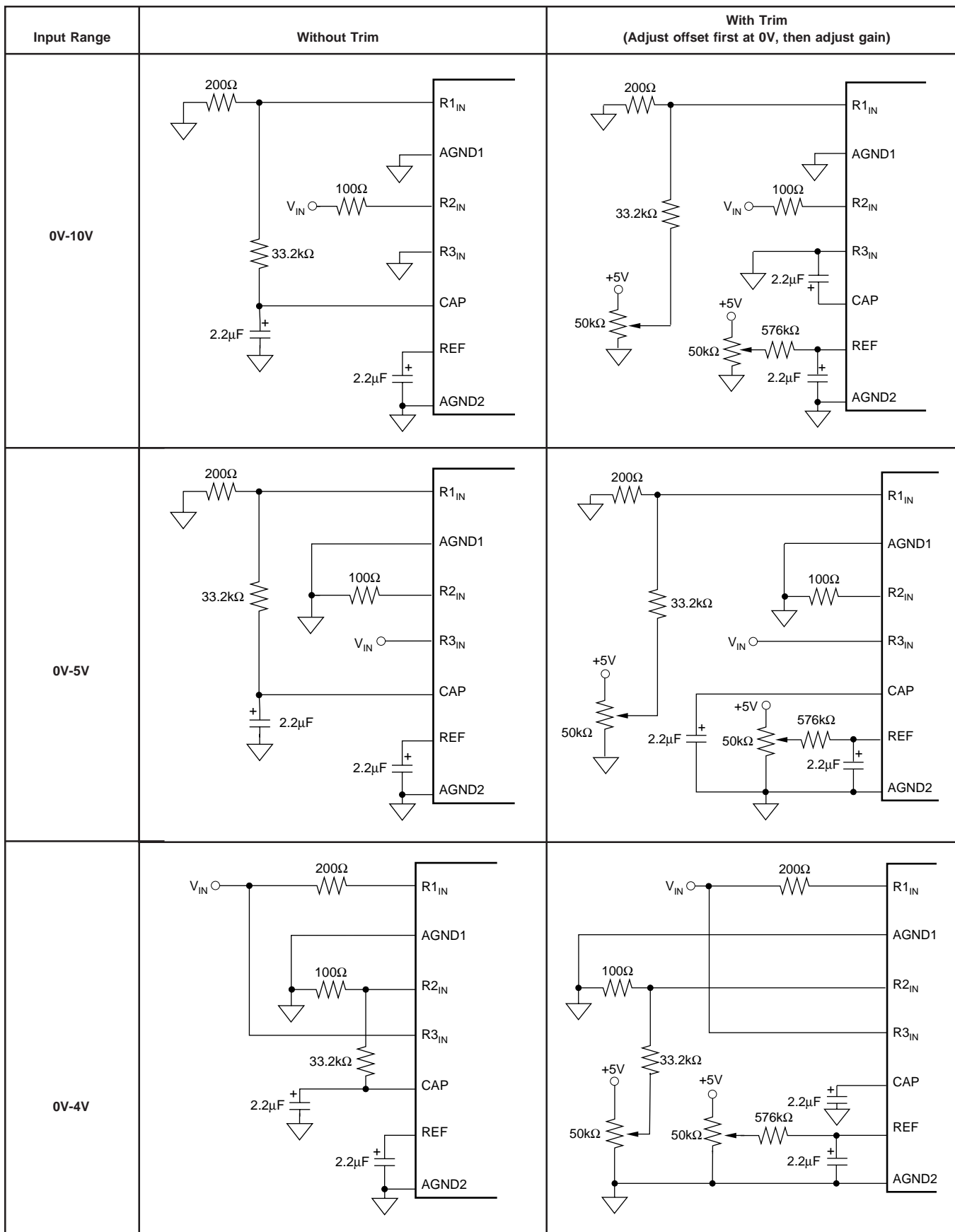


FIGURE 4a. Offset/Gain Circuits for Unipolar Input Ranges.

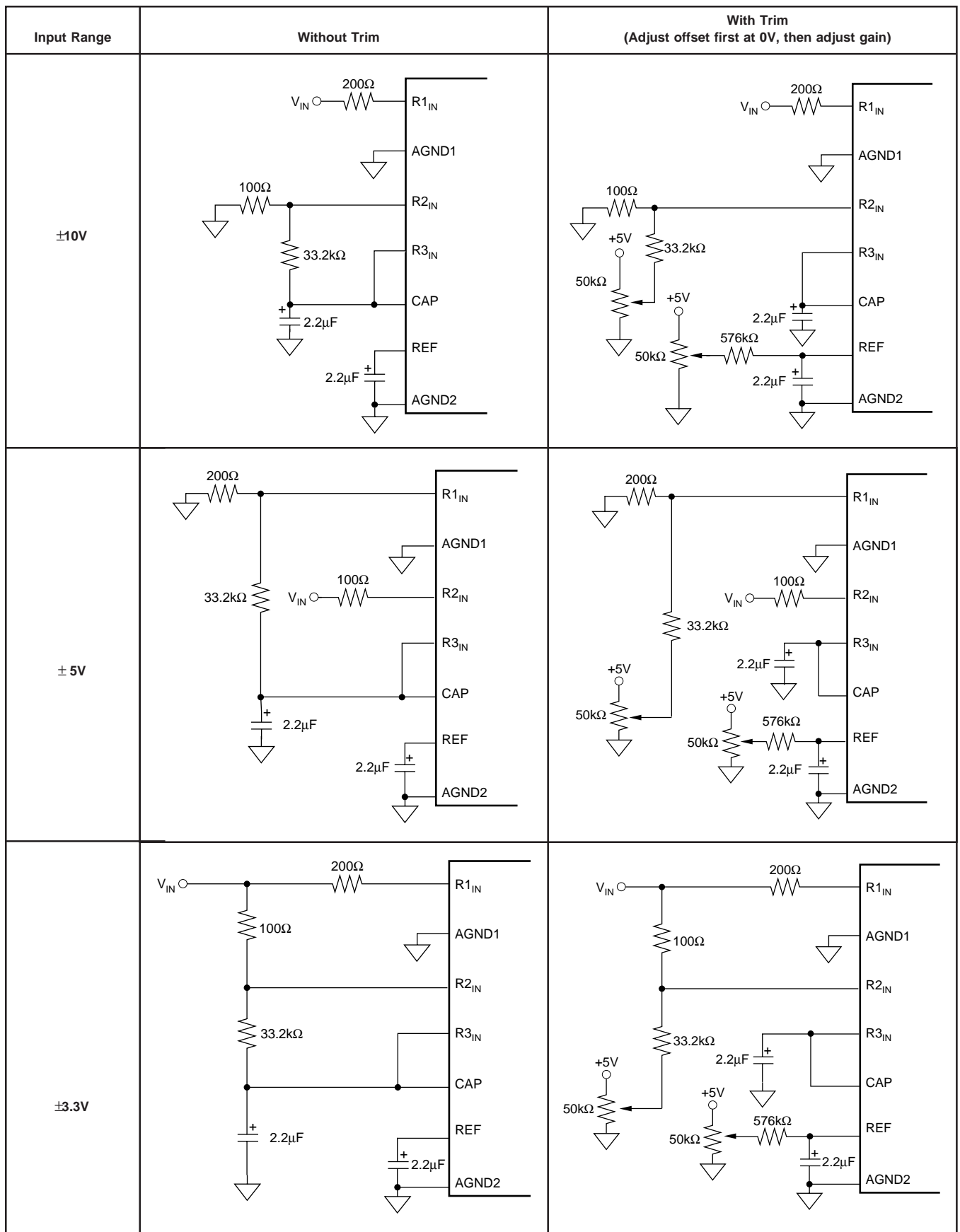


FIGURE 4b. Offset/Gain Circuits for Bipolar Input Ranges.

## Revision History

| DATE  | REVISION | PAGE | SECTION                  | DESCRIPTION                |
|-------|----------|------|--------------------------|----------------------------|
| 10/06 | C        | 3    | Absolute Maximum Ratings | CAP and REF were switched. |

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

**PACKAGING INFORMATION**

| Orderable Device | Status<br>(1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan<br>(2) | Lead finish/<br>Ball material<br>(6) | MSL Peak Temp<br>(3) | Op Temp (°C) | Device Marking<br>(4/5) | Samples                 |
|------------------|---------------|--------------|-----------------|------|-------------|-----------------|--------------------------------------|----------------------|--------------|-------------------------|-------------------------|
| ADS7809U         | ACTIVE        | SOIC         | DW              | 20   | 25          | RoHS & Green    | Call TI                              | Level-3-260C-168 HR  | -40 to 85    | ADS7809U                | <a href="#">Samples</a> |
| ADS7809U/1K      | ACTIVE        | SOIC         | DW              | 20   | 1000        | RoHS & Green    | Call TI                              | Level-3-260C-168 HR  | -40 to 85    | ADS7809U                | <a href="#">Samples</a> |
| ADS7809U/1KE4    | ACTIVE        | SOIC         | DW              | 20   | 1000        | RoHS & Green    | Call TI                              | Level-3-260C-168 HR  | -40 to 85    | ADS7809U                | <a href="#">Samples</a> |
| ADS7809UB        | ACTIVE        | SOIC         | DW              | 20   | 25          | RoHS & Green    | Call TI                              | Level-3-260C-168 HR  | -40 to 85    | ADS7809U<br>B           | <a href="#">Samples</a> |
| ADS7809UB/1K     | ACTIVE        | SOIC         | DW              | 20   | 1000        | RoHS & Green    | Call TI                              | Level-3-260C-168 HR  | -40 to 85    | ADS7809U<br>B           | <a href="#">Samples</a> |
| ADS7809UE4       | ACTIVE        | SOIC         | DW              | 20   | 25          | RoHS & Green    | Call TI                              | Level-3-260C-168 HR  | -40 to 85    | ADS7809U                | <a href="#">Samples</a> |

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

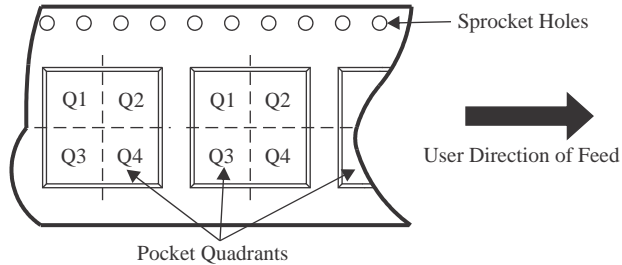
(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


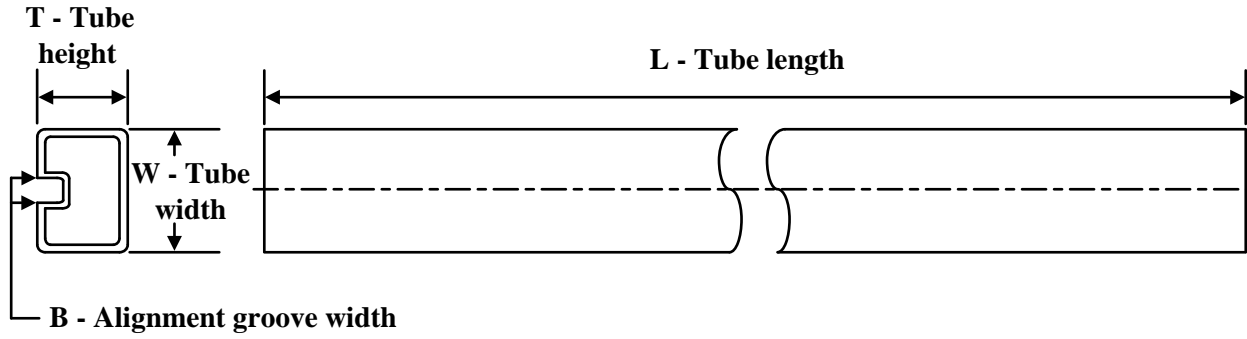
\*All dimensions are nominal

| Device       | Package Type | Package Drawing | Pins | SPQ  | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|--------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| ADS7809U/1K  | SOIC         | DW              | 20   | 1000 | 330.0              | 24.4               | 10.8    | 13.3    | 2.7     | 12.0    | 24.0   | Q1            |
| ADS7809UB/1K | SOIC         | DW              | 20   | 1000 | 330.0              | 24.4               | 10.8    | 13.3    | 2.7     | 12.0    | 24.0   | Q1            |

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

| Device       | Package Type | Package Drawing | Pins | SPQ  | Length (mm) | Width (mm) | Height (mm) |
|--------------|--------------|-----------------|------|------|-------------|------------|-------------|
| ADS7809U/1K  | SOIC         | DW              | 20   | 1000 | 367.0       | 367.0      | 45.0        |
| ADS7809UB/1K | SOIC         | DW              | 20   | 1000 | 367.0       | 367.0      | 45.0        |

**TUBE**


\*All dimensions are nominal

| Device     | Package Name | Package Type | Pins | SPQ | L (mm) | W (mm) | T (μm) | B (mm) |
|------------|--------------|--------------|------|-----|--------|--------|--------|--------|
| ADS7809U   | DW           | SOIC         | 20   | 25  | 507    | 12.83  | 5080   | 6.6    |
| ADS7809UB  | DW           | SOIC         | 20   | 25  | 507    | 12.83  | 5080   | 6.6    |
| ADS7809UE4 | DW           | SOIC         | 20   | 25  | 507    | 12.83  | 5080   | 6.6    |

# DW0020A



# PACKAGE OUTLINE

## SOIC - 2.65 mm max height

SOIC



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**NOTES:**

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
5. Reference JEDEC registration MS-013.

# EXAMPLE BOARD LAYOUT

DW0020A

SOIC - 2.65 mm max height

SOIC



LAND PATTERN EXAMPLE  
SCALE:6X



SOLDER MASK DETAILS

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NOTES: (continued)

- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

DW0020A

SOIC - 2.65 mm max height

SOIC



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE:6X

4220724/A 05/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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